

Abstract:**Method for Simultaneously Cutting a Multiplicity
of Wafers from a Workpiece**

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Method for simultaneously cutting a multiplicity of wafers from a cylindrical workpiece having an axis and a notch applied parallel to the axis in the lateral surface of the workpiece, comprising

10 the application of a cut-in beam on the workpiece, the cut-in beam being fitted from a front side to a rear side with a form fit with a head end in the notch, and protruding out of the notch with a foot end;

holding of the workpiece with its axis parallel to the axes of
15 cylindrical wire guide rollers of a wire saw by means of a feed device of the wire saw;

movement of the cut-in beam and of the workpiece by means of the feed device in a feed direction perpendicularly through a planar wire web consisting of sections, arranged parallel to
20 one another and perpendicular to the axes of the wire guide rollers, of a wire which is guided multiple times in a spiral around the wire guide rollers by means of grooves in the wire guide rollers, the cut-in beam being moved first with the foot end, and the workpiece first with the notch, against the wire
25 web; and

movement of the wire sections in the longitudinal wire direction by rotation of the wire guide rollers in the same sense with the same circumferential speed in the presence of abrasives acting as a grinding agent.

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The drawing for the abstract is: Fig.9